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**FOR IMMEDIATE RELEASE**

DARPA awarded a grant to ISSYS Inc. for the commercialization of its proprietary vacuum packaging technology: NanoGetters™

Integrated Sensing Systems, Inc. (ISSYS) of Ypsilanti, Michigan, announced today that it has won a DARPA contract under BAA-04-10, entitled "A Universal, High-Vacuum, Wafer-Level, MEMS Packaging Technology/Service." This one year project will insert ISSYS' proprietary NanoGetters™ vacuum packaging technology (see <http://www.nanogetters.com/>) into the DARPA supported MEMS Exchange foundry organization <http://www.mems-exchange.org/>. NanoGetters™ technology has been used for several years by ISSYS to produce a variety of MEMS-based products and is now being offered to other microsystem organizations to improve their vacuum packaging capabilities.

NanoGetters™ technology provides great vacuum gettering capability without the problems of particles and contamination encountered with traditional NonEvaporable Getters (NEGs). NEGs have several major disadvantages that NanoGetters™ overcomes including shedding particles during handling and processing plus the requirement for activation of an oxide layer, which reduces the getters effectiveness by consuming getter material.

At the system level perspective, one of the most attractive features that ISSYS' NanoGetters™ technology offers to the MEMS community is a "Total Solution" including:

- High-vacuum (< 1mTorr) encapsulation
- Long-term vacuum stability
- Hermetic electrical lead transfer
- Compatibility with all MEMS technologies (polysilicon surface, bulk, silicon-on glass, and LIGA micromachining technologies)
- Wafer-level fabrication or ceramic packaging (e.g., inclusion and activation of Nanogetter™, and hermetic sealing)
- Particle free vacuum getters
- Low Activation Temperature vacuum getters
- High yield
- Low cost

**Company Background:** ISSYS is a leader in advanced micromachining technologies for medical devices, microfluidic and scientific analytical sensing applications. Founded in 1995 by world-renowned leaders in MEMS technology, ISSYS is one of the oldest independent MEMS companies in the US and has been offering MEMS services longer than any other company in the US. ISSYS

operates a “full manufacturing under one roof” multi-million-dollar, state-of-the-art Bio-MEMS fabrication facility located near Ann Arbor, Michigan. ISSYS offers a high level of quality control standards required by invasive medical products (targeting FDA-compliant manufacturing and European Medical Device Manufacturing, as well as ISO 9000). ISSYS is a vertically-integrated company dedicated to developing and manufacturing system-level products based on MEMS technology (MEMS Inside). For more company, product and service information, please visit <http://www.mems-issys.com/>

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